ISPSD Conference Guidelines

[1] Introduction

The International Symposium on Power Semiconductor Devices and ICs (ISPSD) is a premier international conference for presentation and discussion of all aspects of power semiconductor device and power integrated circuit technologies. The conference is governed by the Advisor Committee (AdCom) and organized each year by organizing committees of the year. The purpose of this document is to provide guidelines to ensure continuity and mutual understanding and application of the key tenets of the conference. The ISPSD Conference Guidelines are published on the official website of the ISPSD conferences.

[2] Revision History

Revision	Authors	Date	Comments	
			Collected input from the advisory	
0	A. Shibib	June 2012	committee and presented in PPT	
			format at the 2012 AdCom meeting	
			Generated separate regulation	
1	M. Mori and K. Hamada	Jan. 2013	documents for Operation, AdCom,	
			and TPC	
2	D. Disney	Mar. 2013	Combined contents of Rev. 0 and 1	
2.1	D. Disney	Mar.23, 2013	Revised version of Rev. 2	
3	M. Mori	Apr. 16, 2013	Comment on Rev. 2.1	
2.4	D. Disney	Apr. 21, 2013	Comments moved into the main	
3.1			document	
3.2	M. Mori	Apr. 22, 2013	Revised version of Rev. 3.1	
3.3	M. Mori	Apr. 23, 2013	Revised version of Rev. 3.2	
3.4	K. Hamada	Apr.24, 2013	Revised version of Rev. 3.3	
2.5		A 24 2042	Accepted all changes into the main	
3.5	D. Disney	Apr. 24, 2013	document	
3.6	M. Mori	May 19, 2013	Revised version of Rev. 3.5	

Revision	Authors	Date	Comments
3.7	M. Mori, K. Hamada, D. Disney	May 26, 2013	Clarified role of secretary and observer at AdCom meetings
4.0	AdCom Members in ISPSD 2013	May 29, 2013	Revision 4.0 authorized at AdCom Meeting in ISPSD 2013
4.1	M. Mori	May 6, 2017	Addition to Appendix I and II
4.2	I. Omura, M. Mori	May 24, 2017	Revised Appendix I
4.3	D. Disney, J. Sonsky, M. Mori	May 30, 2017	Move all comments into the main document
4.4	A. Shibib, H. Ohashi, D. Disney, G. Majumdar, J. Shin, P. Lorenz (sub-committee for Paper Acceptance Criteria)	May 31, 2017 (at AdCom Meeting)	Revised Appendix II
4.5	J. Shen	June 1, 2017	Addition of the ISPSD Hall of Fame
4.6	M. Mori	Sep. 30, 2017	Proposal document
4.7	D. Disney	Oct. 13, 2017	Revised version of Rev. 4.6
4.8	J. Sonsky, J. Shen, M. Mori	Oct. 24, 2017	Revised version of Rev. 4.7
5.0	AdCom Members in ISPSD 2017	Oct. 26, 2017	Revision 5.0 authorized by AdCom Members in ISPSD 2017
5.1	R. Williams, M. Mori	Sep. 22, 2020	Revised version of Rev. 5.0
6.0	AdCom Members in ISPSD 2020	Mar. 19, 2021	Revision 5.1 authorized by AdCom Members in ISPSD 2020

Revision	Authors	Date	Comments
7.0	K. Hamada, J. Shen and AdCom members in ISPSD2021	April.12, 2022	Revised version of 6.0 authorized by AdCom members in ISPSD2021. OA full status; addition of diversity statement; change of incoming AdCom chair process; general streamlining of the language to make it more formal

[3] Mission

The mission of ISPSD is to cultivate an international forum for professionals in the field of power semiconductor devices and smart power integrated circuits and related fields to meet regularly, to exchange ideas and developments in the field, and to promote the growth of the field. The ISPSD AdCom and organizing committee comprise with volunteers with a similar mindset and devotion to advance the field of power semiconductor technology.

[4] Sponsorship

Sponsorship of the ISPSD has traditionally been provided by the IEEE Electron Devices Society (EDS) and technical co-sponsorship has been provided by the IEEE Power Electronics Society (PELS), the IEEE Industry Application Society (IAS), IEE Japan (IEEJ), and other organization when the conference is held in North America. When the conference is held in Japan, sponsorship of the ISPSD has traditionally been provided by the IEEJ with technical co-sponsorship provided by the EDS, PELS, IAS and other organization. When the conference is held in Europe, sponsorship of the ISPSD has traditionally been provided by the EDS with technical co-sponsorship provided by the PELS, IAS IEEJ and the European Center for Power Electronics (ECPE). The sponsorship and technical co-sponsorship for each ISPSD are to be determined by the Organizing Committee for that year's conference.

[5] Registration fees

The registration fees for each ISPSD are to be determined by the Organizing Committee for that year's conference. The Organizing Committee should prepare budget documents in accordance with the sponsoring society for their conference. The IEEE and IEE of Japan members should receive reduced rates to promote society membership. Advance registration fees should be lower than on-site registration fees to promote early registration. Registration fees for student members should be about one half of the standard registration fee to encourage the attendance and participation of students. Students should be allowed to participate in all activities of the conference including panel discussions, receptions, and banquets.

[6] Publications and Copyrights

All papers accepted for presentation at the ISPSD should be published in a Conference Proceedings. This includes all invited, oral, and poster presentations. The copyright of the Proceedings will be assigned to the IEEJ when the conference is held in Japan and to the IEEE when the conference is held in any location outside of Japan. The IEEE should receive the ISBN Catalog Number for all of the Proceedings so that they may be distributed to all libraries and other entities affiliated with the IEEE.

[7] Advisory Committee

Purpose

The purpose of the ISPSD Advisory Committee (AdCom) is to foster communication among the organizing committees and regions, to oversee the long-term development of the conference, and to ensure consistent application of the key tenets of the conference. This AdCom is the top decision-making organization of the ISPSD. It is responsible for documenting and enforcing the ISPSD Conference Guidelines and for approving conference locations and appointment of General Chairs, Steering Committee Chairs, and Technical Program Committee (TPC) Chairs.

Membership

AdCom members are the past ISPSD General Chairs. The AdCom member list and attendance record is maintained by the AdCom Chair and approved each year by the voting members at the AdCom meeting. The General Chairs are invited to become observers of the AdCom during the four years in advance of the ISPSD conference that they organize. An observer will have a voice but no vote at AdCom meetings. At the beginning of the conference that the General Chair organizes, the General Chair changes from an AdCom observer to an AdCom member and the AdCom chir. The Steering Committee Chair (if applicable) and the TPC Chair during the four years in advance of their ISPSD conference are invited to attend the AdCom meeting held during the conference as secretaries. Secretaries will record the meeting minutes and have no voice and no vote.

Each year, the AdCom Chair should contact all AdCom members and confirm their intention to continue serving at the end of the ISPSD that year. If an AdCom member does not attend an AdCom meeting for four consecutive years, the AdCom Chair should ask that member to resign from the AdCom.

AdCom Chair

The General Chair of each conference is invited to serve as the AdCom Chair from the beginning of the conference that they organize to the beginning of the following year's conference. If this person cannot or will not serve, then the AdCom will elect an AdCom Chair from the list of the AdCom members.

Meetings

The AdCom will meet once per year, during the ISPSD conference. The incoming AdCom Chair, with the support of the outgoing AdCom Chair, has the responsibility of arranging and hosting the AdCom meeting, setting the agenda, and writing and distributing the meeting minutes. Any AdCom member may place items on the AdCom meeting agenda by submitting those items to the incoming and outgoing AdCom Chairs in advance of the meeting. Decisions of the AdCom will be determined by a vote of the members in attendance, and a 2/3 vote of the attending members will be required in order for a measure to be approved. Approved measures will be documented in the AdCom meeting minutes and, if appropriate, in the ISPSD Conference Guidelines. The outcoming AdCom Chair has the responsibility of handing over the ISPSD documents and information to the incoming AdCom Chair.

[8] Conference Operations

Frequency and Location

The ISPSD is held once per year, typically in May or June. The conference currently rotates each year among Japan (JP), North America (NA) Europe (EU) and Other Areas (OA) in a four-year cycle. Future ISPSD conference locations and General Chair appointments should be proposed by AdCom and/or TPC members from the hosting region and approved by the AdCom. Criteria for approval may include historical contributions to the ISPSD and, experience and capability of the proposing team as well as location suitably. The approval decision should be made at an AdCom meeting at least two years prior to the proposed conference.

Chairs

At least three years prior to the next conference, the AdCom members from the region will nominate candidates to serve as General Chair and TPC Chair (and Steering Chair, if applicable).

The candidates will present a conference proposal, including conference location/venue and organizing team to the AdCom for approval. It is recommended that the General Chair candidates should have served for at least three years on the TPC and at least one year on the Organizing Committee of the previous ISPSD conference.

The General Chair of each ISPSD will have the primary responsibility for management and operation of that year's conference. A Steering Committee Chair may be appointed to assist the General Chair in carrying out these responsibilities if the region decides to do so.

The TPC Chair will determine the membership of the TPC, in accordance with these guidelines, listed in this document, and lead the TPC in the process of paper selection, publication, and presentation at the conference.

ISPSD is committed to advancing diversity in the conference, and to promoting an inclusive and equitable culture in its activities and programs that welcomes, engages and rewards those who contribute to the field without regard to race, religion, gender, disability, age, national origin, sexual orientation, gender identity, or gender expression.

[9] Technical Program Committee

The primary functions of the TPC are to solicit abstracts, to review them, and to select papers for publication and presentation at the ISPSD.

Organization

The TPC includes one TPC Chair, a Sub-committee Chair for each Sub-committee, and several TPC members. The target size of the TPC is about 15% of the average conference attendance. As of March 2013, the target membership is 60 people including the TPC Chair and Sub-committee Chairs, based on an average attendance of about 400 for the past three years. The target membership number may be adjusted by the AdCom as indicated by attendance patterns and other factors.

Sub-committees

The TPC comprises several sub-committees (i.e. tracks) based on technology categories. As of March 2017, the sub-committees are:

• High voltage devices (HV)

- Low voltage devices and power IC device technology (LVT)
- Power IC design (ICD)
- GaN and nitride base compound materials: Device and Technology (GaN)
- SiC and other materials: Device and Technology (SiC)
- Module and Package Technologies: System Integration in Package (PK)

As the industry and conference evolve, the AdCom should review, redefine, add, combine, and remove categories, as appropriate. [Appendix I]

Responsibilities

The TPC Chair is responsible for the selection of Sub-committee Chairs and TPC members [Appendix III], and administration of the paper selection process [Appendix II]. Sub-committee Chairs are responsible for assisting the TPC Chair in the evaluation and selection of the papers assigned to their Sub-committee.

TPC members are expected to review and score all papers assigned by the TPC Chair, and to participate in the paper selection meeting. The TPC Chair and Sub-committee Chairs may also serve as paper reviewers. TPC members should review the assigned papers personally without involving others in the reviewing them. Moreover, no representative will be allowed to attend the paper selection meeting on behalf of a TPC member.

Paper Selection Meeting

The venue and schedule of the paper selection meeting will be decided by the TPC. The meeting is preferably held in early December of the year prior to the ISPSD. The venue will be decided based on the convenience for all TPC members under consideration of the host region. This meeting is preferably held during some related conference or workshop, for example the IEDM, of the year prior to the ISPSD meeting, in order to foster participation by all TPC members from every region. Internet-based meeting access should be arranged for those TPC members who are unable to attend the meeting.

TPC members should not score those papers written by authors from the same affiliation (first authors or co-authors). During the paper selection meeting, TPC members should leave the

paper selection meeting room whenever a paper by authors from their affiliation is being discussed.

TPC members have an obligation to keep the contents of submitted papers confidential.

Membership

The TPC Chair should be nominated by the AdCom members from the region in which the meeting will be held, and should be approved by the AdCom. The Sub-committee Chairs should be appointed by the TPC Chair. The TPC Chair is responsible for selecting the TPC members for the ISPSD conference that he/she is organizing. The following are guidelines for determining the TPC membership.

- 1. Members of the TPC should be recognized experts in the field of the Sub-committee on which they serve.
- 2. Industry, academia, and national labs should be represented in fair proportion to the number of contributions from the respective category.
- 3. Each region (Japan, North America, Europe, and Other Area) should be represented in fair proportion to the number of contributions from the respective region.
- 4. AdCom members, former General Chairs, and former TPC Chairs from each region should be consulted regarding TPC membership from their region.
- New TPC members may be nominated by existing members of the TPC, AdCom, and/or Organizing Committee.
- 6. Preference should be given to candidates that exhibit the ISPSD values of open-minded thinking, high level technical ability, and good communication.
- 7. There should be no more than two TPC members from the same affiliation, and no more than one Sub-committee member from the same affiliation.
- 8. Members should serve a maximum of five consecutive years on the TPC and then take a break of at least 2 years before being asked to re-join the TPC. This policy will allow about 80% of existing members to serve in the following year, ensuring consistency, while also allowing regular opportunities for new people to participate.

- 9. Each year's TPC Chair should strive to improve membership balance among the regions and sub-committees.
- 10. To maintain regional balance, the target number of TPC members on each Sub-committee should be divided among the regions. An example of the target committee membership that provides equal representation is shown below. Regional representation in each Sub-committee could also be determined based on long-term trends in paper submission and presentation volume.

Dogian	HV	LVT	ICD	GaN	SiC	PK	Total TPC
Region	subcom	subcom	subcom	subcom	subcom	subcom	members
Japan	2 to 3	15					
North America	2 to 3	15					
Europe	2 to 3	15					
Other Area	2 to 3	15					
Total	8 to 12	60					

[10] Plenary Sessions

The plenary session should consist of a minimum of one invited paper to a maximum of four invited papers (no more than one paper per one region) from the geographic regions of Japan, North America, Europe, and Other Area. The final selection of the plenary speakers is the responsibility of the Organizing Committee. It is recommended that the Organizing Committee consult with AdCom members from each region to identify appropriate speakers from their respective regions.

[11] Awards

<u>The Charitat Award</u> should be awarded each year to a young researcher (age less than 30 at the time of the conference) who is both a first author and presenter of a paper determined to be best overall among all eligible papers. Paper eligibility should be indicated during the abstract submission process. The Charitat award should be administered by the TPC each year and presented during the closing session of the conference. Traditionally, the Charitat

award has been decided by a vote in a committee comprising a subset of the TPC and including fair representation from all of the regions.

<u>The Ohmi Best Paper Award</u> should be awarded every year to the authors of a paper determined to be the best overall by a popular vote of all TPC members in attendance at the conference. The process should be administered by the TPC Chair with a goal of announcing the winner to the TPC members during the TPC dinner or equivalent gatherings. The best paper award should be presented by this TPC Chair at the opening session of the following year's ISPSD.

The Pioneer Award has been awarded to individuals who were deemed to have made seminal contributions to the advancement of any of the ISPSD fields of interest. This award has traditionally been given to a person who made their most significant contributions while working in the region that is hosting that year's ISPSD. There has also been a bias toward recognizing an individual who has not yet received recognitions that are commensurate with their contributions. Pioneer Award recipients were determined by the Organizing Committee with input from the TPC. Starting in 2018, the Pioneer Award was discontinued in favor of the new ISPSD Hall of Fame recognition.

<u>The ISPSD Contributory Award</u> has been presented occasionally for outstanding service to the conference. These awards were administered by the AdCom. AdCom members nominated potential awardees and the entire AdCom voted to determine whether or not the nominees should be presented with a Contributory Award. Starting in 2018, the Contributory Award was discontinued in favor of the new ISPSD Hall of Fame (IHF) recognition.

The ISPSD Hall of Fame

The purpose of the IHF is to honor individuals who have made high impact contributions in advancing power semiconductor technology and/or in sustaining the success of the ISPSD. Starting in 2018, the IHF replaced the "Contributory Awards" and "Pioneer Awards." The IHF inductee list will be "permanently" displayed on the ISPSD website from year to year.

An IHF Selection Committee will be appointed by the ISPSD AdCom which should include the next General Chair of the ISPSD as a voting member. The selection committee is preferably a Sub-committee of the AdCom. The IHF Selection Committee accepts nomination from all

sources, particular those from the Organizing Committee of the next ISPSD. The criteria for Induction into the IHF requires:

- 1. High-impact contributions to any of the ISPSD fields of interest
- 2. Significant and sustained contributions to the field presented at ISPSD; and/or
- 3. Demonstrated leadership to sustain the success of the ISPSD conference.

The IHF is intended for individuals who have demonstrated a longstanding commitment to the field of power semiconductors and to the ISPSD community with significant contributions dating back at least ten years. Except for special circumstances, the number of award recipients per year shall be limited to two persons. Generally, IHF award recipients will be selected and receive their award at an ISPSD conference held in the geographic region in which they made their contributions.

[Appendix I]

Technology categories of sub-committees were revised by the AdCom meeting of ISPSD2017

1. High voltage devices (HV)

High voltage silicon based discrete devices (> 200V), including:

- •IGBTs, thyristors, GTOs, and PiN diodes
- •Superjunction MOSFETs and new unipolar devices
- High voltage power device failure mechanisms
- Wafer technology and lifetime controls
- New gate drive methods to enhance IGBT and Superjunction MOSFET performance
- •Safe operating areas and current filament effects in IGBT
- New edge terminations
- Simulation or measurement technologies related to this category

2. Low voltage devices and power IC device technology (LVT)

Low voltage silicon base discrete power devices (≤ 200V) and power devices for power ICs for all voltage ranges, including:

- High performance power MOSFET for DC-DC converters
- •LIGBT, LDMOS for 600V power ICs
- •SOI power devices for power ICs
- Power device designs on BCD technology
- Device isolation technologies
- MOSFET structures for level shifters
- Process integration for low voltage power devices
- SOA of LDMOSFETs
- •Simulation / measurement technologies related to this category Footnote:

The LVT category covers device designs, device ideas and device physics etc..

3. Power IC design (ICD)

Circuit design and demonstration using power IC technology platform, including:

• Gate driver circuit design including WBG power device applications

- Circuit design for SiC and GaN based IC
- •New circuit and layout design enhancing power IC performance
- •Single chip inverters and converters
- •New signal isolation technology on power IC such as magnetic coupling
- •Power SoC and passive component integration on a chip
- •ESD protection circuit
- •Compact circuit model for power IC design
- New type of hybrid power ICs
- Modeling, design platform and measurement technology for power IC

Note: ICD category covers power IC circuit design, system integration, IC architecture, etc.

4. GaN and nitride base compound materials: Device and Technology (GaN)

GaN and nitride base power devices technology and integration, including:

- AlGaN/GaN hetero devices
- Vertical GaN MISFETs,
- •AIN power devices
- •Special circuit and application for GaN and nitride base power devices
- •GaN and nitride base power IC technologies
- Special application for GaN and nitridel devices
- •New process integration for GaN power ICs
- •Simulation/measurement technology related to this category

5. SiC and other materials: Device and Technology (SiC)

SiC and other material base power devices technology and integration, including:

- •SiC power MOSFET, IGBT, and SIT devices and process development
- •SiC power IC technologies
- Diamond power devices
- •Gallium oxide power devices
- Special application for SiC and other material devices
- New process technology for SiC and other material devices
- •Simulation/measurement technology related to power device

6. Module and Package Technologies: System Integration in Package (PK)

Module and Package technology for discrete power devices and power ICs, including

- •Power module, transfer molded package demonstration
- •Power module design including wire frame
- •Chip current and temperature measurement
- Pressure contact packages for high power system applications
- •Thermal management and new cooling technology
- •Stress and strain simulation for package structures and materials
- •3D-package and stray inductance management
- Package design against noise and switching losses
- •Reliability physics and failure analysis related to package design and material
- Package insulation technology and material, high temperature endurance
- Power SiP hardware design
- Application specific aspects (considering system integration e.g. different sub-topology, etc.)
- •Simulation/measurement technology related to this category

[Appendix II]

The purpose of Paper Acceptance Criteria (PAC) in the paper selection process is:

- to keep the ISPSD as the premier technical conference for Semiconductor Power Devices & ICs
- 2. to promote technical sharing of ideas, trends, and innovations in the field
- 3. to remain as the best conference to attend for experts or new researchers, practicing engineers, and students so that they can learn and share their experiences about new innovations in the field of devices and applications.

The PAC consists of two-tier systems with technical items and material content/presentation quality. The submitted papers are put in 6 technical items with different weighing factors (WF). Each item has 5-grade ratings of material content/presentation quality. The total score for each submitted paper is the sum of 6 technical item points, multiplied by the rating point of the quality by the WF of each item [Table]. The WFs of each item are proposed by the General Chair and TPC Chair (and the Steering Chair, if desired), and approved by AdCom members.

Table. Evaluation Table for Paper Acceptance Criteria (PAC): Sample

Items of PAC	Novelty of	Potential	Experimental	Theoretical	Clarity of	Review
	concept	impact	support	or simulation	figures and	of prior work
		Including		support	technical	
		applications			writing	
Weighing(A) Rating(B)	1.0	1.0	0.9	0.7	0.8	0.6
4	Excellent	Creating New Field	Excellent	Excellent	Excellent	Excellent
3	Good	Radical Impact	Good	Good	Good	Good
2	Interesting	Incremental Impact	Average	Average	Average	Average
1	Minor Change	Small Impact	Poor	Poor	Poor	Poor
0	Nothing	Nothing	Nothing	Bad	Bad	Nothing
ΑxΒ	3.0	2.0	0	2.1	2.4	1.2

Total Score: Σ (A x B) = 10.7 (MAX: 20.0)

[Appendix III]

TPC members have a very important role in selecting high quality papers, which is critically important to keep the ISPSD as the premier technical conference for Semiconductor Power Devices & ICs, and to remain as the best conference to attend for expert or new researchers, practicing engineers and students so that they can learn and share their experiences about new innovations in the field of devices and applications.

TPC member selection is conducted in accordance with two-tier systems of affiliation and personal comprehensive knowledge and ISPSD contributions based on the clause [9] in these Guidelines.

- Accepted paper points (APPs) for the past ten years are listed for each affiliation.
 APPs are 2 points for an oral paper and 1 point for a poster paper, respectively.
 Co-authors share points proportionately on an affiliation basis.
- 2. An Expert with personal comprehensive knowledge and high ISPSD paper quality in each affiliation with high APPs is elected as a TPC member by the TPC Chair.
- 3. The TPC chair counts APPs and sends them to the next TPC Chair.